

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHIUN-WEI CHAN	07/25/2011
CHIH-HSUN KE	07/25/2011
RECEIVING PARTY DATA	
Name:	ADVANCED OPTOELECTRONIC TECHNOLOGY, INC.
Street Address:	No. 13, Gongye 5th RD., Hsinchu Industrial Park, Hukou Shiang
City:	Hsinchu Hsien 303
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13191469
CORRESPONDENCE DATA	
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Phone:	9099786584
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Correspondent Name:	Raymond J. Chew
Address Line 1:	288 South Mayo Avenue
Address Line 4:	City of Industry, CALIFORNIA 91789
ATTORNEY DOCKET NUMBER:	US36405
NAME OF SUBMITTER:	Raymond J. Chew
Total Attachments: 2 source=US36405110727ASM#page1.tif source=US36405110727ASM#page2.tif	

CH \$40.00 13191469

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. SHIUN-WEI CHAN , residing at Hukou, Hsinchu, Taiwan
- 2. CHIH-HSUN KE , residing at Hukou, Hsinchu, Taiwan
- 3. _____ , residing at _____
- 4. _____ , residing at _____
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **ADVANCED OPTOELECTRONIC TECHNOLOGY, INC.** having a principal place of business at **No. 13, Gongye 5th Rd., Hsinchu Industrial Park, Hukou Shiang, Hsinchu Hsien 303, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **METHOD FOR PACKAGING LIGHT EMITTING DIODE** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>SHIUN-WEI CHAN</u> SHIUN-WEI CHAN	<u>Ju1.25,2011</u> Date
2.	<u>CHIH-HSUN KE</u> CHIH-HSUN KE	<u>Ju1.25,2011</u> Date
3.	_____	_____ Date
4.	_____	_____ Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date